

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau

(43) International Publication Date
20 February 2025 (20.02.2025)



(10) International Publication Number
WO 2025/038366 A1

- (51) **International Patent Classification:**
GI1C 29/02 (2006.01) *G01R 31/3185* (2006.01)
H01L 29/66 (2006.01) *H01L 29/04* (2006.01)
H01L 29/51 (2006.01) *H01L 29/786* (2006.01)
H01L 29/78 (2006.01) *H01L 21/28* (2006.01)
G06F 1/18 (2006.01) *H10B 51/30* (2023.01)
63/567,649 20 March 2024 (20.03.2024) US
63/637,742 23 April 2024 (23.04.2024) US
63/637,764 23 April 2024 (23.04.2024) US
63/674,471 23 July 2024 (23.07.2024) US
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- (81) **Designated States** (*unless otherwise indicated, for every
kind of national protection available*): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,
- (21) **International Application Number:**
PCT/US2024/041392
- (22) **International Filing Date:**
08 August 2024 (08.08.2024)
- (25) **Filing Language:** English
- (26) **Publication Language:** English
- (30) **Priority Data:**
63/518,988 11 August 2023 (11.08.2023) US
63/602,733 27 November 2023 (27.11.2023) US
63/602,737 27 November 2023 (27.11.2023) US

(54) **Title:** METHOD AND SYSTEM FOR TESTING STACKED FACE-TO FACE BONDED CHIPLETS

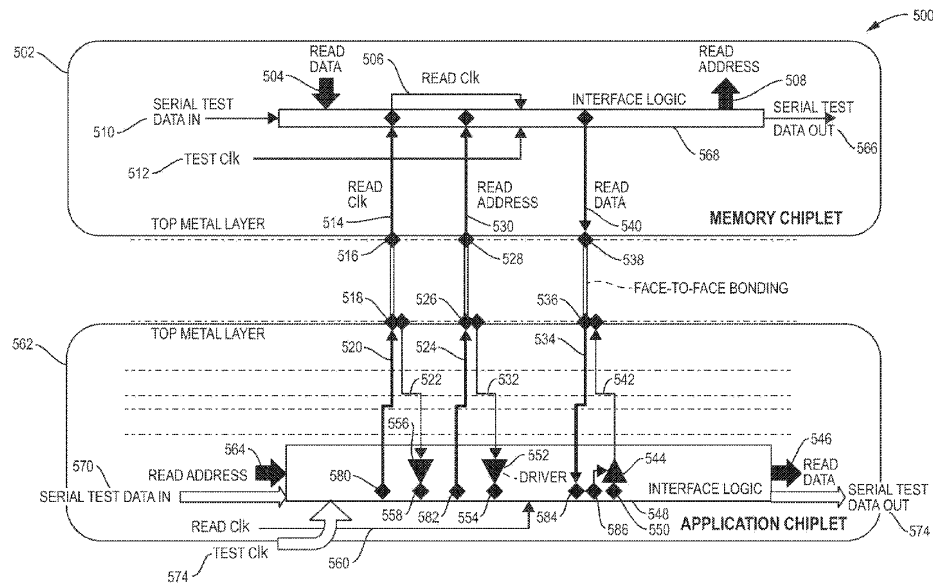


FIG. 5

(57) **Abstract:** A method, and related systems, of making a known-good stack are disclosed. The method includes forming a first semi-conductor device having an interface logic with a plurality of interconnects electrically coupled to a surface of the first semiconductor device. The method also includes activating an interconnect loopback configured to receive a first one of the plurality of interconnects and electrically communicate back to the interface logic through the interconnect loopback. The method electrically couples a test signal to the first one of the plurality of interconnects and tests a return signal returned from the interconnect loopback to thereby test a path from the first one of the plurality of interconnects and through the interconnect loopback back to the interface logic.

[Continued on next page]

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CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM,
DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG,
KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY,
MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA,
NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO,
RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH,
TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS,
ZA, ZM, ZW.

(84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, CV, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))